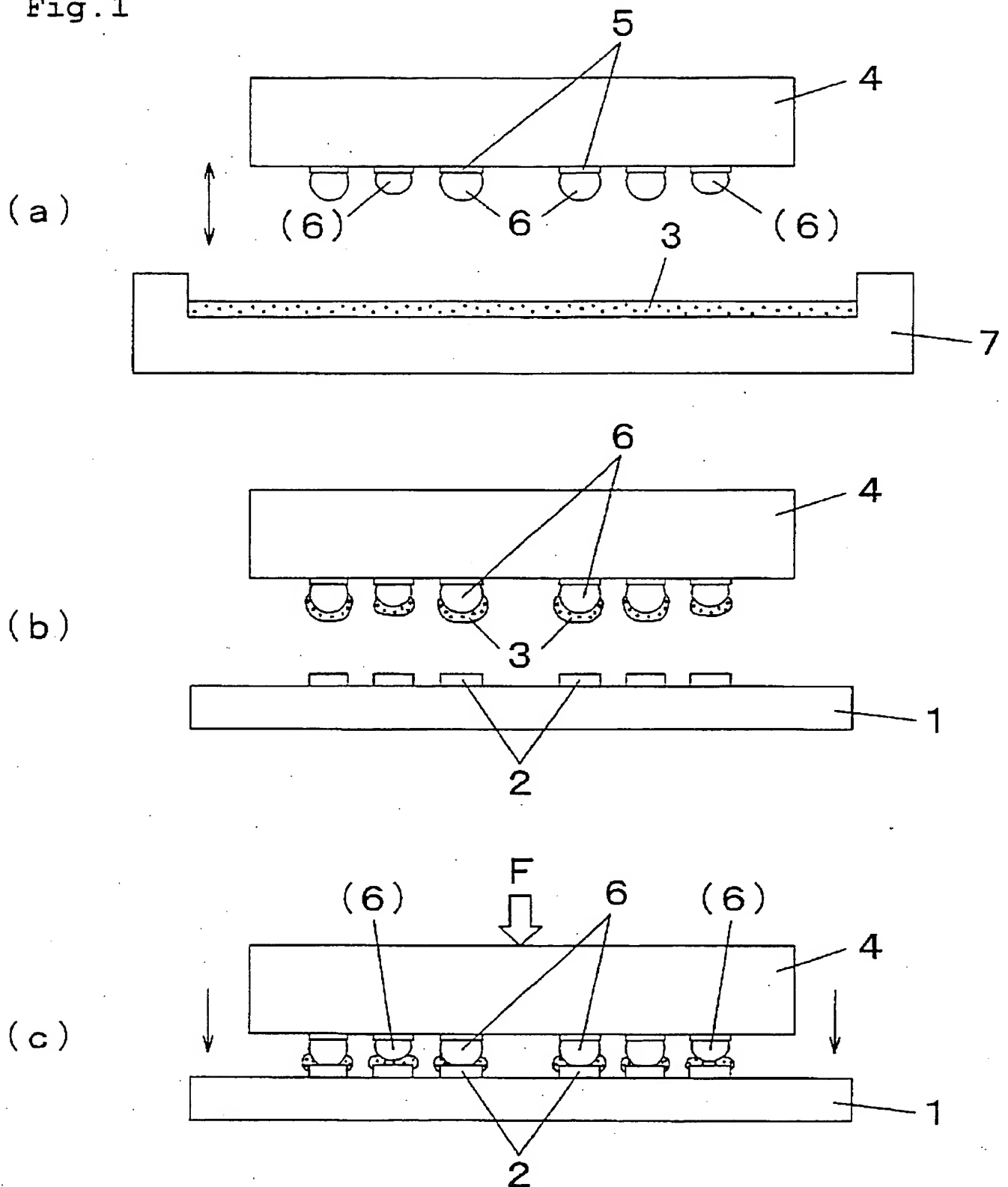


Fig. 1



1 substrate

3 flux

5 external connection electrode

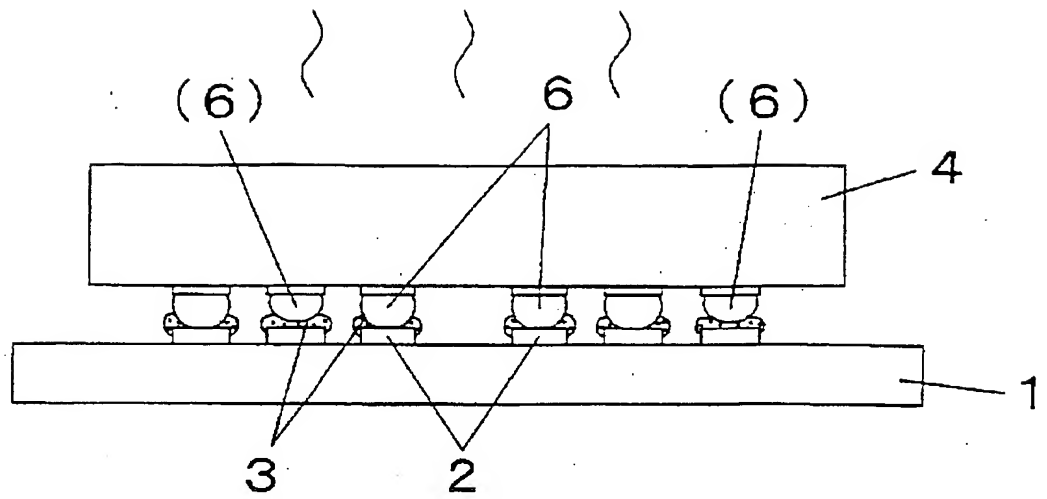
2 circuit electrode

4 electronic part

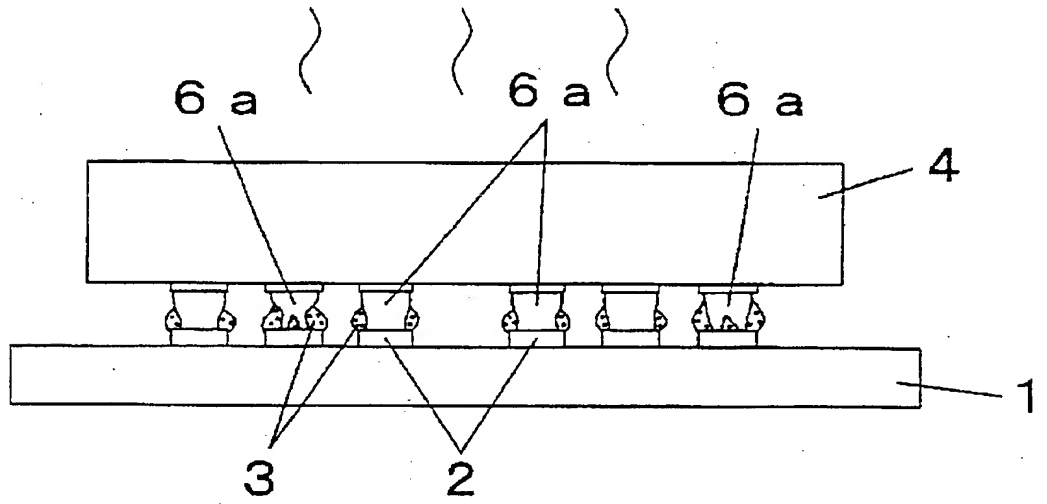
6 bump

Fig. 2 .

(a)



(b)



(c)

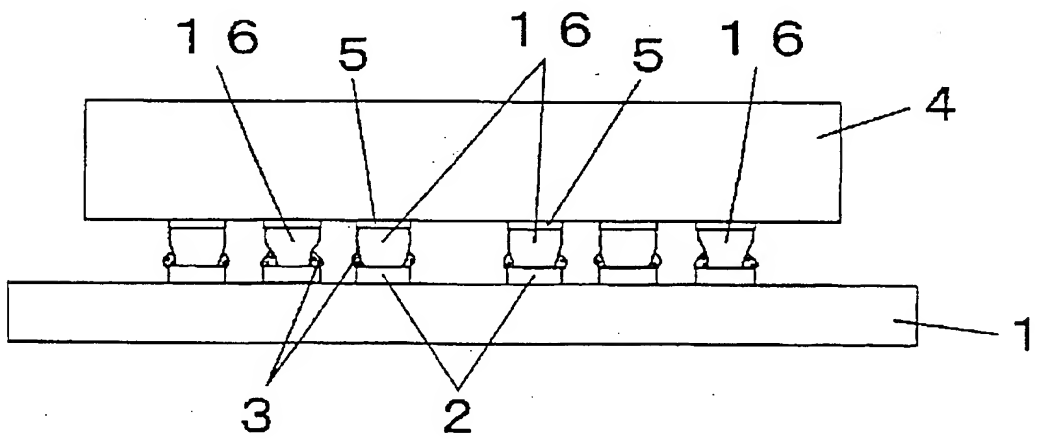
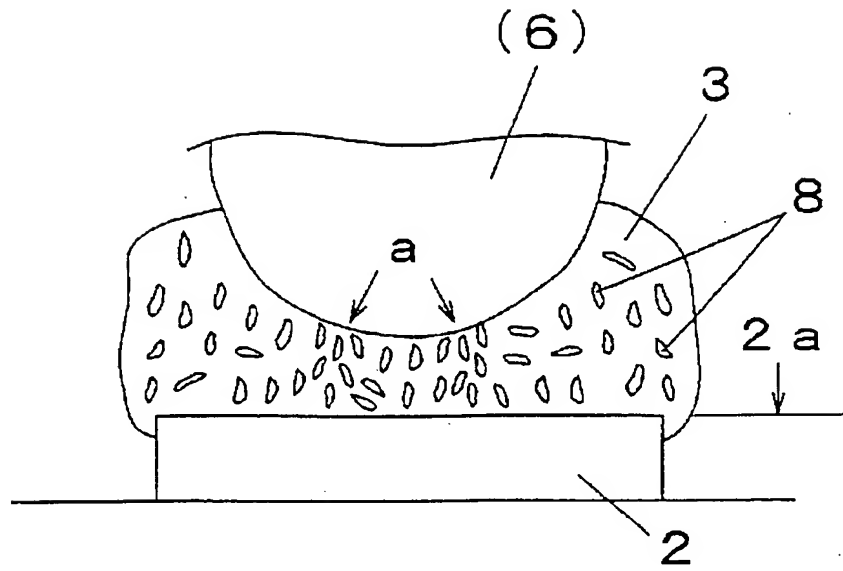
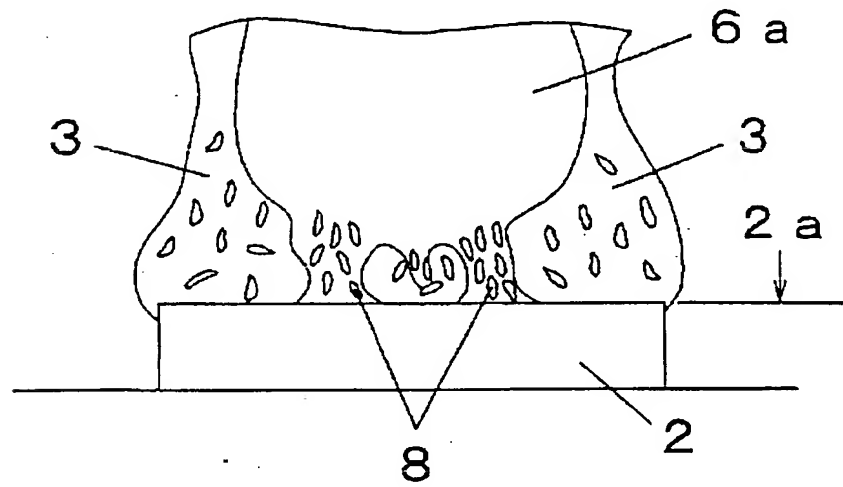


Fig.3 .

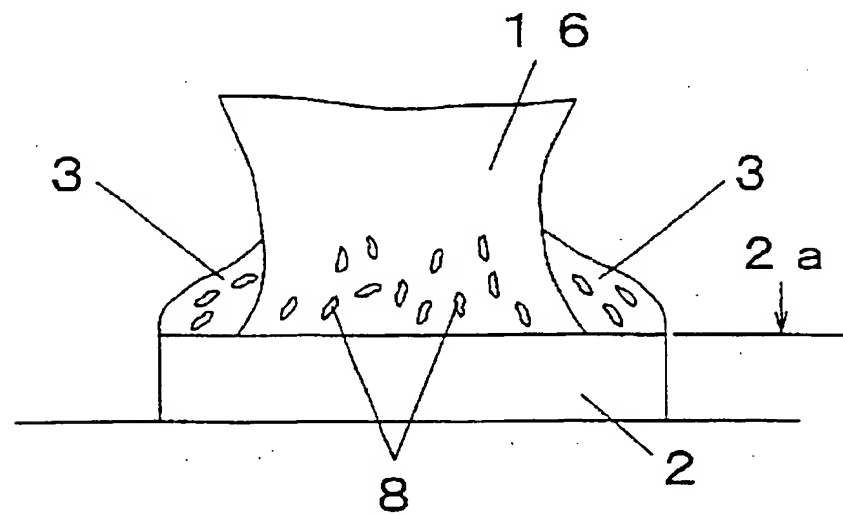
(a)



(b)



(c)



8 metal powder

Fig. 4

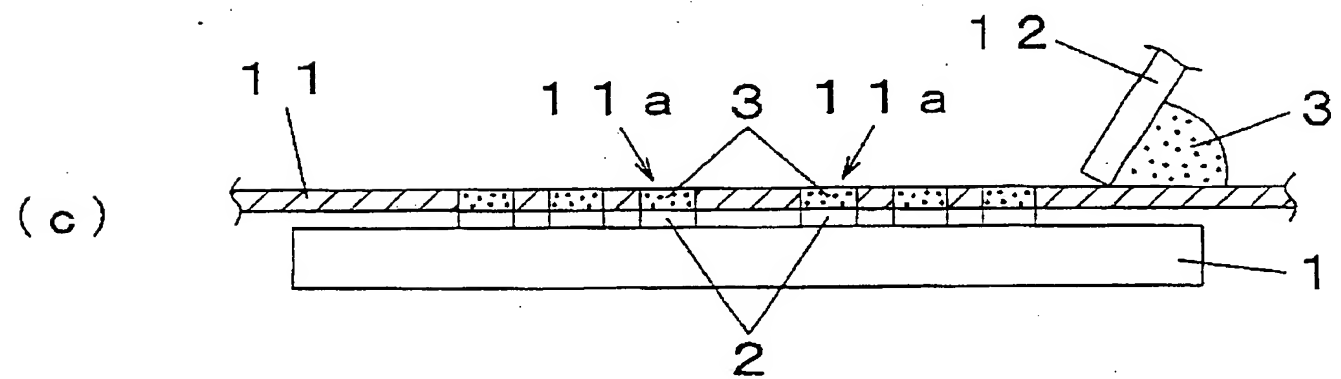
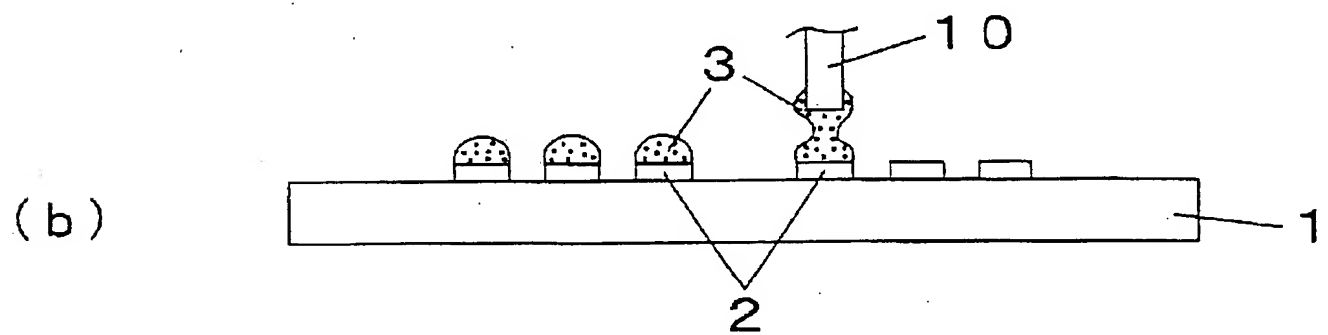
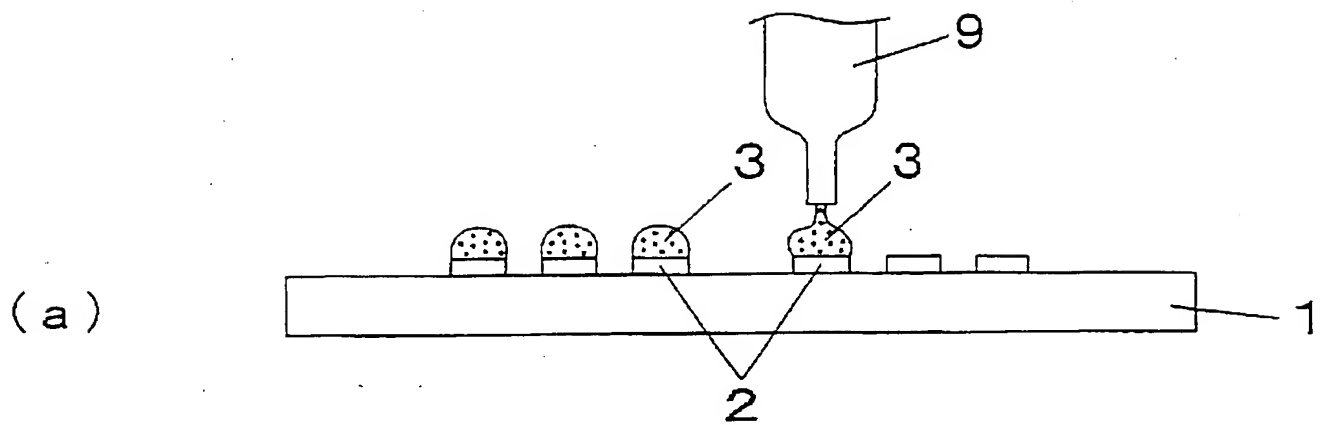


Fig. 5

poor connection ratio (%)

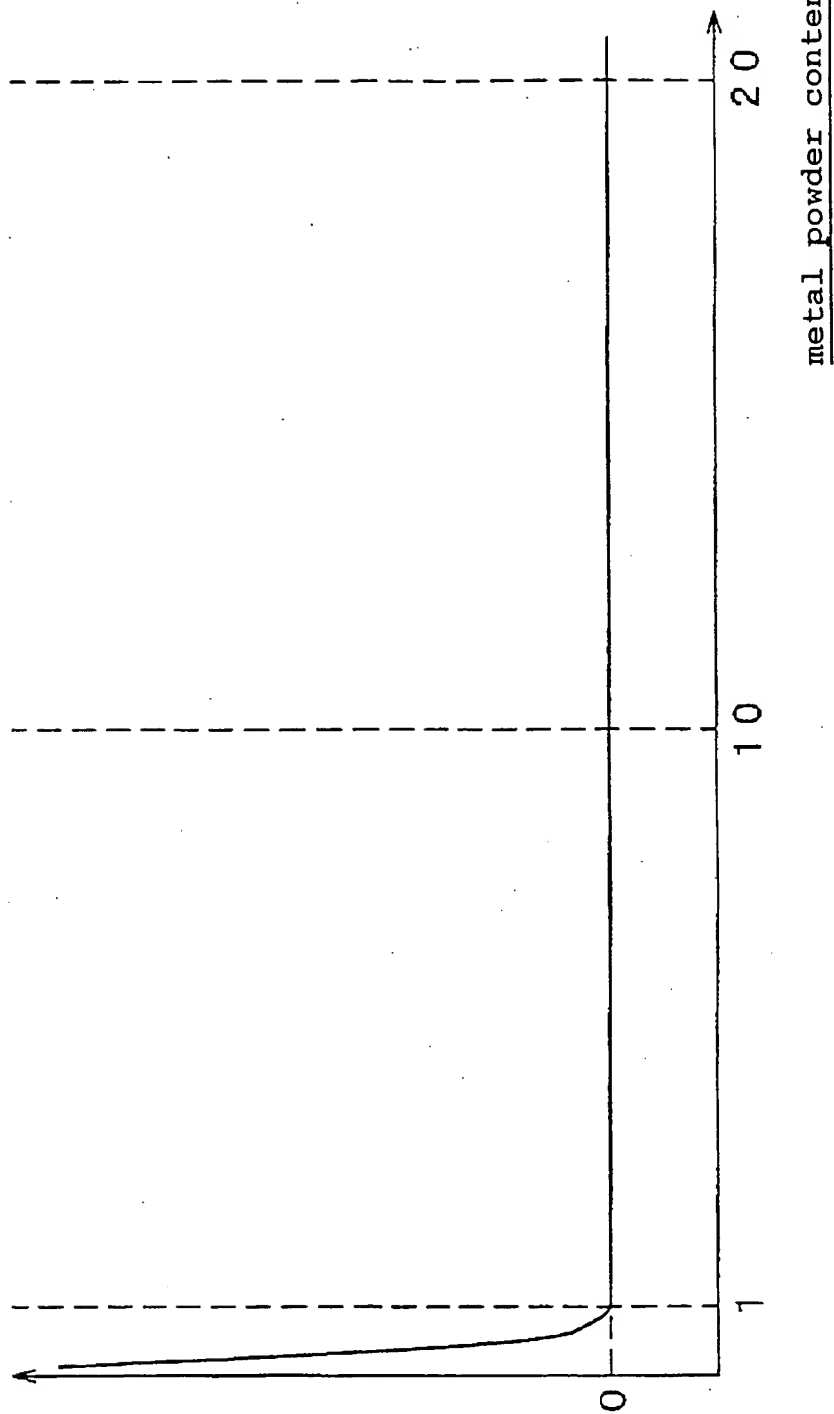


Fig. 6

